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ASMC 2013 - TABLE OF CONTENTS

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Session 1 - Advanced Patterning/ Design for Manufacturing

1.1 **Cost Effective Application of Advanced Computational Lithography Techniques Using Flexible Mask Optimization** **1**

Gek Soon Chua, Yi Zou, Wei-Long Wang, GLOBALFOUNDRIES; Jianhong Qiu, Taksh Pandey. Stanislas Baron, Sanjay Kapasi, Russell Dover, Xiaolong Zhang, Bo Yan, ASML Brion

---

1.2 **Fast and Accurate Design Based Binning Based on Hierarchical Clustering with Invariant Feature Vectors for BEOL** **7**

Katsuyoshi Miura, Yuki Soga, Koji Nakamae, Osaka University; Kenichi Kadota, Toshiyuki Aritake, Yuichiro Yamazaki,Toshiba Corporation

---

1.3 **Characterization methodology to support process development of advanced patterning structures** **13**

Shailendra Mishra, Alok Vaid, Lin Zhou, Han Taejoon, Hyunchul Jung, Liping Cui, Luo Meng, Shi Yong Jun, Thaung-Htun Oo, Wen Pin Peng, Yue Hu Jesper, GLOBALFOUNDRIES; Cornel Bozdog, Paul Isbester, Oded Cohen, Nova Measuring Instruments, Inc.

1.4 **Feasible Industrial Fabrication of Thin Film Transistor based on Randomized Network of Single Walled Carbon Nanotube** **18**

Sayed Alireza Mousavi, Patrizia Lamberti, Vincenzo Tucci, University of Salerno; Veit Wagner, Jacobs University Bremen

---

1.5 **Investigation of Shape Etching on Multi-layer SiO2/Poly-Si for 3D NAND Architecture** **24**

Zusing Yang, Fang-Hao Hsu, Lo Yueh Lin, Hong-Ji Lee, Nan-Tzu Lian, Tahone Yang, Kuang-Chao Chen and Chih-Yuan Lu Macronix International Co.

Session 2 - Factory Optimization I

2.1 **Designing Product Workflow for Logistics – a Hidden Potential for Cycle Time and Cost Reduction as well as Quality Improvement in High-Tech-Factories** **27**

Sophia Keil, Rainer Lasch, Dresden University of Technology ; Dietrich Eberts, Infineon Technologies Dresden

---

2.2 **An Effective Problem Decomposition Method for Scheduling of Diffusion Processes Based on Mixed Integer Linear Programming** **35**

Chihyun Jung, Detlef Pabst, Myoungsoo Ham, Marcel Stehli, Marcel Rothe, GLOBALFOUNDRIES Inc.

2.3 **Optimizing Multi-Station Scheduling in Consideration of Equipment Flexibility and Loading Balance in Semiconductor Wafer Fabrication** **41**

Ya-Tang Chuang, Yi-Hung Chang, Jr-Fong Dang, Ren-Chyi You, Steven M. Chang, Taiwan Semiconductor Manufacturing Company

2.4 **Lean Manufacturing Improvements - Supercharging Direct Observation with Ethnography** **45**

Matthias H. Giessler, Geraldine Fagan, Dan Jaggers, Intel Corporation

2.5 **Demand Smoothing** **51**

Allison Rose Bannister, Jeanne P. Bickford, Karl Swanke, IBM

Session 3 - 3D/TSV Technology

3.1 **Novel Photodefined Polymer-Clad Through-Silicon Via Technology Integrated With End Point Detection Using Optical Emission Spectroscopy** **56**

Paragkumar A. Thadesar, Ashish Dembla, Gary S. May, Muhannad S. Bakir, Georgia Institute of Technology; Ja Myung Gu, Sang Jeen Hong, Myongji University

3.2 **Challenges in Thin Wafer Handling and Processing** **62**

Stephen Olson, Klaus Hummler, Brian Sapp, SEMATECH

3.3 **Mechanical Characteristics of Thin Dies/Wafers in Three Dimensional Large-Scale Integrated Systems** **66**

Mariappan Murugesan, T. Fukushima, J.C. Bea, K.W. Lee, H. T. Tanaka, M. Koyanagi, Tohoku University

3.4 **TSV Density Impact on 3D Power Delivery with High Aspect Ratio TSVs** **70**

Huanyu He, James J-Q. Lu, Rensselaer Polytechnic Institute; Zheng Xu, Xiaoxiong Gu, IBM

3.5 **Metrology and Inspection Challenges for Manufacturing 3D stacked IC's** **75**

Sandip Halder, Karen Stiers, Andy Miller, Ingrid de Wolf, Mireille Maenhoudt, Eric Beyne; IMEC, Stefano Guerrieri, Micron Technology

Session 4 - Factory Optimization II

4.1 **Organizational Learning and Capital Productivity in Semiconductor Manufacturing** **80**

Charles M. Weber, Jiting Yang, Portland State University

4.2 **Eradicating Human Errors during Preventive Maintenance: Understanding the Psychological Reasons We Make Errors and Implementing Proactive Practices to Manage and Reduce Human Errors** **87**

Peter Gaboury, Angeline Ottolini, Bruno Spanu, Gerard Chaix, Laurence Philippon, STMicroelectronics

4.3 **Automation: Key to Cycle Time Improvement in Semiconductor Manufacturing** **93**
Amit Sonar, Satyajit Shinde, Susanto Teh, GLOBALFOUNDRIES

4.4 **Automated Metrology Recipe Creation** **99**
Andrew Haskins, Andre Holfeld, GLOBALFOUNDRIES

4.5 **Deploying an Equipment Health Monitoring Dashboard and Assessing Predictive Maintenance** **105**
James Moyne, Jimmy Iskandar, Parris Hawkins, Applied Materials; Toysha Walker, Micron; David Stark, ISMI; Avi Furest and Bryan Pollard, Intel Corporation

Session 5 - Interactive Poster Session

5.1 **The Analysis of Process Queue Time in a Foundry Environment** **111**
Michael Alan Retersdorf, Ulf Lederer, GLOBALFOUNDRIES

5.2 **A Bottom-Up Search Technique of Manufacturing Indicators** **115**
Jacques Pinaton, STMicroelectronics; Sara Bouzid, Corine Cauvet, Claudia Frydman, LSIS laboratory

5.3 **Cu/Ni Interface Study for Bump Reliability Improvement** **121**
Rung-De Wang, Taiwan Semiconductor Manufacturing Company, Ltd.

5.4 **Design-enabled Manufacturing Enablement using Manufacturing Design Request Tracker (MDRT)** **126**
Akif Sultan, Rao Desineni, Jens Hassmann, Kristina Hoeppner, Eswar Ramanathan, Carl Babcock, Kok Peng Chua, Edward Teoh, Vito Dai, Sky Yeo, Colin Hui, Luigi Capodieci, Sarah McGowan, Robert Madge GLOBALFOUNDRIES

5.5 **Die Level Defects Detection in Semiconductor Units** **130**
Asaad Said, Nital Patel, Intel Corporation

5.6 **Efficiency in Sealing: A BKM Case Study** **134**
Dalia Vernikovsky, Applied Seals North America; Brad Ecker, Seth Urbach, Microchip Technology

5.7 **Equipment Automation Framework with embedded Interface-A** **138**
Bert Müller, Jochen Kinauer, AIS Automation Dresden GmbH

5.8 **Glass Substrates for Carrier and Interposer Applications and Associated Metrology Solutions** **142**
Aric B. Shorey, John T. Keech, Corning Incorporated

5.9 **Improvement of Lithography Process by Using SMO for 14nm FINFET Application** **N/A**
Jung Yu Hsieh, Yayi Wei, GLOBALFOUNDRIES

A Lean Approach to Human Performance **151**

5.10 *Michael E. Lombardi, Intel Corp.*

5.11 **Maintaining Abatement Efficiency while Increasing Utility Efficiency Using the Applied iSYSTM Controller** .... %))
Monique McIntosh, Applied Materials

5.12 **New Vaporization Sources for H2O2 for Pre-treatment/Cleaning of ALD Deposition Surfaces** .... %) -
Dan Alvarez, Jr. Jeff Spiegelman, Andrew Kummel, Tobin Kaufman-Osborn, Kiarash Kiantaj, Russell J. Holmes, Ed Heinlein, Lita Shon-Roy, Bhuvnesh Arya, RASIRC

5.13 **The N2 diluted application in PECVD NF3 in-situ chamber cleaning for PFC reduction** .... %* '
Ming-Huei Chen, C.T. Ni, C.H. Su, Y.L. Chen, TSMC

5.14 **Overlay Mark Contrast Enhancement for Double Patterning** ... B#5
Sohan Singh Mehta, Herrick Matthew, Tsai Huai-Hsuan, Lokesh Subramany, Michael Anderson, Jeon Bumhwan, Yayi Wei, GLOBALFOUNDRIES

5.15 **Purging of Front Opening Unified Pod for 450 mm Wafer Manufacturing** .... %+ %
Chun-Yong Khoo, Shih-Cheng Hu, Tze-Yu Huang, Cheng-Wei Yang, National Taipei University of Technology

5.16 **Qualification Management and Its Impact on Capacity Optimization** .... %+ (
Mehdi Rowshannahad, Stéphane Dauzère-Pérès, Ecole des Mines de Saint-Etienne; Bernard Cassini, Soitec

5.17 **Practical aspects of Virtual Metrology and Predictive Maintenance model Development and Optimization** .... %, $
U. Schöpka, Lothar Pfitzner, G. Roeder, A. Mattes, M. Schellenberger, M. Pfeffer, P. Scheibelhofer, ams AG/Graz University of Technology

5.18 **A Process to Reduce the Occurence of Metal Extrusions in Al Interconnects** .... %, *
Shawn Adderly, IBM Microelectronics

5.19 **Rough Film Wafer Sensitivity Improvement using Light Scattering Inspection System** .... %- %
Chuanyong Huang, Raymond Chu, Gordana Nešković, KLA-Tencor

5.20 **Simulations of "Atomistic" Effects in Nanoscale Dopant Profiling** .... %- (
Petru Andrei, Mohit Mehta, Florida State University; Mark Hagmann, Newpath Research

Session 6 - Yield Enhancement I

6.1 **Effective Co-optimization of DFM and Defect Inspection Methods for Fast Yield Ramp** .... &$$
Yan Pan, Rao Desineni, Jane Lambert, Edward Teoh, Victor Lim, Goh Szu Huat, Thomas

Berndt, GLOBALFOUNDRIES; John Kim, Sagar Kekare, Synopsys

6.2 **Use of Performance Path Test to Optimize Yield** ....&$*
Jeanne Paulette Bickford, Jinjun Xiong, IBM

6.3 **Statistical Correlation of Inline Defect to Sort Test in Semiconductor Manufacturing** ....&%&
Uwe Hessinger, Brett Schafman, Wendy Chan, Toan Nguyen, Shiree Burt, Lattice Semiconductor Corporation

6.4 **Heading Towards Big Data: Building A Better Data Warehouse For More Data, More Speed and More Users** .....&&$
Raymond Goss, Kousikan Veeramuthuk GLOBALFOUNDRIES

6.5 **Case Studies of Fault Isolation for the Global Failing Patterns on SRAM Bitmap caused by the Defects in Peripheral Logic Regions** ....&&*
Jianhua Yin, Jian Yu, Sheng Xie, Dapeng Sun, Yong Ern Ling, GLOBALFOUNDRIES; Zhigang Song, Carl E. Schiller, Genadi Teverskoy, Manuel J. Villalobos, IBM

Session 7 - Advanced Metrology I

7.1 **Composition Measurement Of Tri-layer SiGe Stack Using Broadband Spectroscopic Ellipsometry** .....&' %
Michael Anderson, Felipe Tijiwa Birk, Alok Vaid, GLOBALFOUNDRIES; Leander Haensel, Ronny Haupt, Carlos Ygartua, Frank Shu, KLA-Tencor

7.2 **MBIR for In-line Doping Metrology of Epitaxial SiGe:B and SiC:P Layers** ....&' +
Romain Duru, Delphine LE-CUNFF, Yves Campidelli, D. Barge, STMicroelectronics; Nicolas Laurent, Jonny Hoglund, Semilab

7.3 **Full Wafer Nanotopography Analysis on Rough Surfaces Using Stitched White Light Interferometry Images** ....&('
Dirk Lewke, Martin Schellenberger, Lothar Pfitzner, Fraunhofer Institute of Integrated Systems and Device Technology (IISB); Thomas Fries, Bastian Tröger, Alexander Muehlig, FRT GmbH; Frank Riedel, Stefan Bauer, Hubert Wihr, Siltronic AG

7.4 **3D X-Ray Microscopy: A Non-Destructive High Resolution Imaging Technology That Replaces Cross-Sectioning for 3D IC Packaging** .....&(-
Yuri Andrade Sylvester, Luke Hunter, Bruce Johnson, Xradia; Tulip Chou, TSMC

7.5 **Leveraging Applied Materials TechEdge PrizmTM for Advanced Lithography Process Control** .....&) *
Paul Llanos, Roger Cornell, Applied Materials

Session 8 - Defect Inspection I

8.1 **Optimizing Inspection Recipes by Using Virtual Inspector Virtual Analyzer and** .....&* &

Failure Bitmap
Roma Jang, Dongchul Ihm, Byoungho Lee, Samsung Electronics Co. Ltd; Gangadharan Sivaraman, Chang Ho Lee, Jian Wu, Graham Lynch, George Simon, Poh Boon Yong, KLA-Tencor

8.2 **Leveraging Puma DF Wafer Inspection to Characterize Root Cause of Yield Loss on an advanced 32 Nm HKMG SOI Technology Device** ······&*)
Alisa Blauberg, Tom Timberlake, Andrew Stamper, Daniel Jaeger, MaryJane Brodsky, Renee Mo, IBM Corporation; Gangadharan Sivaraman, Jeff Barnum, Gary Crispo, KLA-Tencor

8.3 **Defect Sampling Methodology for Yield Learning During 22nm Process Development** ········&*,
Julie Lee, Chen Xu, Vikas Sachan, Oliver D. Patterson, IBM

8.4 **Systematic Edge Inspection for Defect Reduction** ·······&+&
Pratik Joshi, R. Van Roijen, J. Coffin, S. Conti, P. Flaitz, J. Eastman, IBM

Session 9 - Advanced Equipment Processes and Materials

9.1 **Advanced Process Control for Furnace Systems in Semiconductor Manufacturing** ······&+)
Amit Sonar, Satyajit Shinde, Yulei Sun, GLOBALFOUNDRIES

9.2 **Pre-Clean Synergy with Poly CMP Process** ······&, $
Lai Kah Keen, Goh, Wooi Cheang; Chen Yan; Peck, Yan Zheng; Park, Won Gyu; GLOBALFOUNDRIES (Singapore) Pte Ltd

9.3 **Novel Process Strategies for Strip over TiN** ·····&, *
Li Diao, Vijay Vaniapura, Robert Mueller, Mattson Technology, Inc.

9.4 **Methods of Removing Solvent-like Residues from Wafer Backside Bevel** ····&- %
Sheng-Yuan Chang, Cheng-Yi Lung, An Chyi Wei, Hong-Ji Lee, Nan-Tzu Lian, Tahone Yang, Kuang-Chao Chen and Chih-Yuan Lu; Macronix International Co., Ltd.

Session 10 - E-Beam Inspection

10.1 **Early Detection of Systematic Patterning Problems for a 22nm SOI Technology using E-Beam Hot Spot Inspection** ·····&-)
Oliver D. Patterson, Deborah A. Ryan, Mike D. Monkowski, Dominique Nguyen-ngoc, Bradley Morganfeld, IBM; Chung-ham Lee, Chieh-hung Liu, Chi-ming Chen, Shih-tsung Chen, Hermes Macrovision Inc.

10.2 **Early Detection of Electrical Defects in Deep Trench Capacitors using Voltage Contrast Inspection** ····' $%
Brian Donovan, Oliver D. Patterson, W. Chang, N. Arnold, B. Messenger, O. Kwon, J. Liu, IBM; Roland Hahn, KLA-Tencor

10.3 **E-beam Inspection for Gap Physical Defect Detection in 28nm CMOS Process** ·········' $+

Tsung Chih Chen, Chen Nan Tsai, White Pai,United Microelectronics Corporation; Curious Wu, Fei Wang ,Luke Lin, Hermes Microvision

10.4 **E-beam Inspection of EUV Programmed Defect Wafers for Printability Analysis** ......' %$
Ravi Bonam, Scott Halle, Daniel Corliss, IBM; Hung-Yu Tien, Fei Wang, Wei Fang, Jack Jau, HMI

Session 11 - APC

11.1 **Case of Small-Data Analysis for Ion Implanters in the Era of Big-Data FDC** ....' %)
Keung Hui, Jason Mou, Taiwan Semiconductor Manufacturing Company

11.2 **Characterization and Real Time Fault Detection of Vacuum Leaks in Plasma Nitridation Tools** .....' &$
Joseph F. Shepard, Jr., Mark L. Reath, IBM Microelectronics; James K. Wilson, Applied Materials

11.3 **Virtual Metrology for Prediction of Etch Depth in a Trench Etch Process** ....' &*
Georg Roeder, Martin Schellenberger, Lothar Pfitzner, Fraunhofer Institute of Integrated Systems and Device Technology (IISB); Sirko Winzer, Stefan Jank, Infineon Technologies

11.4 **Application of PCA for Efficient Multivariate FDC of Semiconductor Manufacturing Equipment** ....' ' &
Alexis Thieullen, Mustapha Ouladsine, Aix-Marseille University; Jacques Pinaton, STMicroelectronics

Session 12 - Yield Enhancement II

12.1 **Defect Reduction by Nitrogen Purge of Wafer Carriers** ......' ' ,
Raymond Van Roijen, P. Joshi, S. Conti, W. Brennan, P. Findeis, IBM; D. Bailey, PDF Solutions

12.2 **Single Wafer Cleaning Lessons in Advanced Node Gate Module Development** ......' (&
David F. Hilscher, Daniel Jaeger, Charlotte DeWan, Maryjane Brodsky, Ryan Rettmann, IBM Semiconductor Research and Development Center

12.3 **Hybrid Clean Approach for Post Copper CMP Defect Reduction** ......' (*
Wei-Tsu Tseng, Vamsi Devarapalli, James Steffes, Adam Ticknor, Mahmoud Khojasteh, Praneetha Poloju, Colin Goyette, David Steber, Leo Tai, Steven Molis, Mary Zaitz, Elliott Rill, Surbhi Mittal, Michael Kennett, Laertis Economikos, George Ouimet, Christine Bunke, Connie Truong, Stephan Grunow, Michael Chudzik, IBM

Session 13 - Advanced Metrology II

13.1 **Scatterometry-based On-product Focus Measurement and Monitoring** .... ') &
Timothy A. Brunner, Cheuk W. Wong, Pawan Rawat, IBM SRDC; Paul Hinnen, Vivien Wang, Hossein Mardanpour, Jan Beltman, Erica Rottenkolber, Christian Leewis, ASML

13.2 **Advanced Litho-Cluster Control via Integrated In-Chip Metrology** ...... ' * $
Kaustuve Bhattacharyya, Henk-Jan H. Smilde, Arie den Boef, Andreas Fuchs, Steffen Meyer, ASML Netherlands B.V.; Chih-Ming Ke, Guo-Tsai Huang, Kai-Hsiung Chen, Taiwan Semiconductor Manufacturing Company, Ltd.

13.3 **Automated Transmission Electron Microscopy for Defect Review and Metrology of Si Devices** ...... ' * *
Michael Strauss and Mark Williamson, FEI Company

Session 14 - Defect Inspection II

14.1 **GaN-On-Si Process Defect Detection and Analysis for HB-LED's and Power Devices** .... ' +%
Sandip Halder, Karen Stiers, Prem Kumar Kandaswamy, Maarten Rosmeulen, Laureen Carbonell, Yoga Saripalli, Haris Osman, Erik Rosseel, imec; Antonio Mani, Srinivas Vedula, Marco Polli, KLA-Tencor

14.2 **Detecting Yield Limiting SiGe Defects for 28nm Ramping** .... ' +)
Elston Chen, Wen Pang Lin, Garry Chen, P Y Chiang, White Pai, United Microelectronics Corporation; Sam Chen, Mahatma Lin, Frank Jin, Eros Huang, Harvey Cheng, Tetsuya Yamamoto, KLA-Tencor Corporation

14.3 **On the Generation and Elimination of Lonely Poly-Silicon Crater-Defects and their Impacts on Gate Oxide Integrity (GOI) in Dual-Gate Technology** ..... ' +,
Lieyi Sheng, Paul Porath, Eddie Glines, ON Semiconductor

14.4 **In-situ Detection of Photoresist Failures** .... ' , &
Farhad Mirian, Thomas Bitzer, Infineon Technologies AG

Session 15 - Advanced Equipment Processes and Materials

15.1 **Recent Advances in Memory Technology** .... ' , *
Dick James, Chipworks Inc.

15.2 **Integrating Spin-Torque-Transfer Magnetic Memory in a 65 nm Low Power CMOS Technology** .... ' - *
Douglas Coolbaugh, Michael Liehr, Michelle Pautler, College of Nanoscale Science and Engineering; Rajiv Ranjanb, Ebi Abedifard, Avalanche Technology

15.3 **Improving Electric Behavior and Simplifying Production of Si-Based Diodes by Using Thermal Laser Separation** ...... ($$
Matthias Koitzsch, Dirk Lewke, Martin Schellenberger, Lothar Pfitzner, Heiner Ryssel, Fraunhofer Institute of Integrated Systems and Device Technology (IISB); Robert Kolb, Robert Bosch GmbH; Hans-Ulrich Zühlke, Jenoptik Automatisierungtechnik GmbH

15.4 **Contamination Control and Pilot Manufacturing of Commercial Grade Carbon Nanotube Colloidal Formulations** ....($(
Billy Smith, Thomas Kocab, Rahul Sen, David A. Roberts, Nantero Inc.